

IN THE SPECIFICATION

Please amend the Specification as follows:

On page 1, lines 1-2, please amend the Title as follows:

METHOD OF FORMING CLOSED AIR GAP INTERCONNECTS AND STRUCTURES FORMED THEREBY A CLOSED AIR GAP INTERCONNECT STRUCTURE

On page 27, lines 19-23, please amend the paragraph as follows:

Next, following an optional wet or dry clean to remove any residues caused by the etch process, the line and via openings are filled with a thin conformal conductive liner 2130 by means of either a physical vapor deposition (PVD), atomic layer deposition (ALD) or a chemical vapor deposition (CVD) process.